

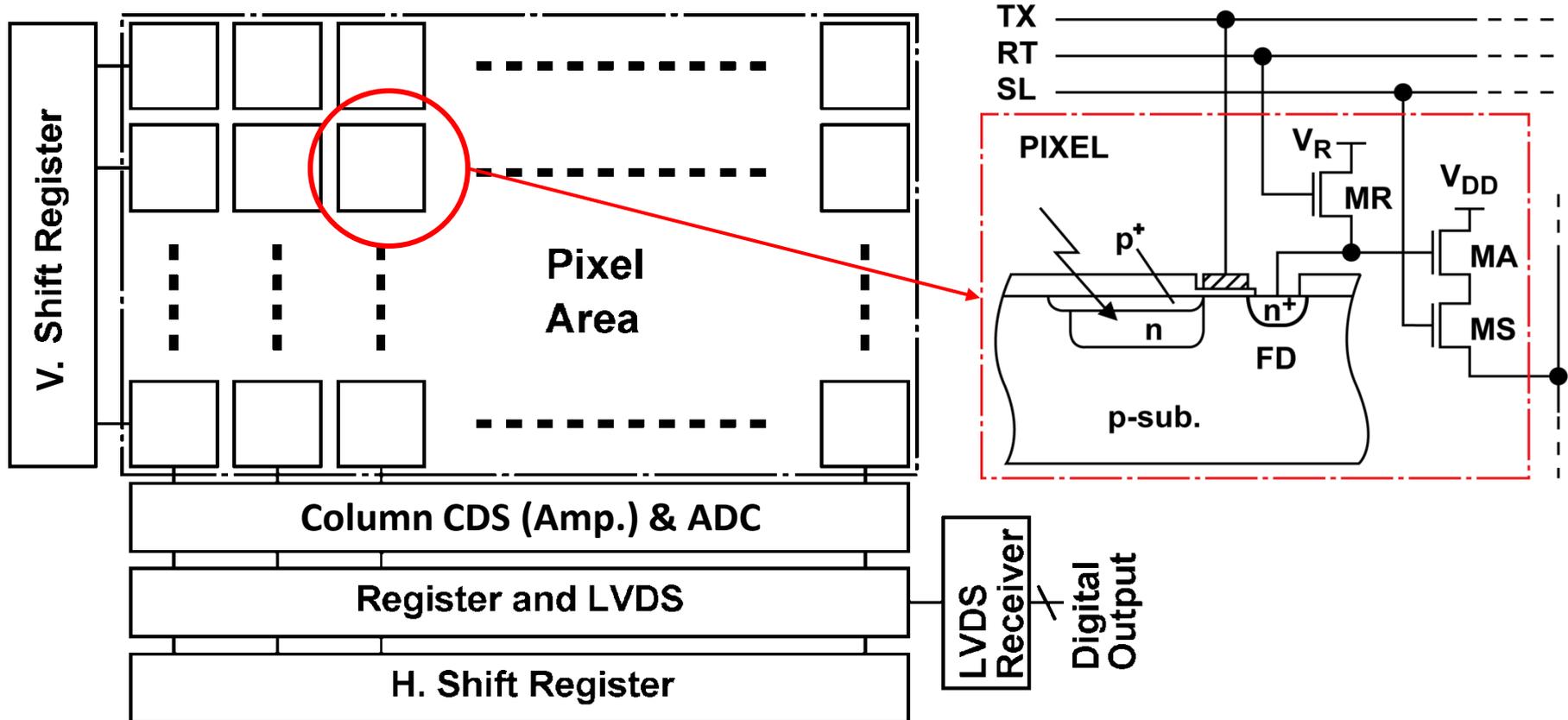
History and prospect of low-noise CMOS sensors

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Typical CIS Architecture



- Charge-transfer-type active pixel with pinned photodiode
- Column CDS (Correlated double sampling) Amplifier (**if necessary**)
- High-speed A/D conversion Using 1-D parallel operation
- High-speed low-noise digital signaling like LVDS (low-voltage differential signaling)

Low Noise CMOS Image Sensors: Design Challenges

1. Low Noise ($<2e^-$)
2. Low Noise at High Pixel Rate (= frame rate x # of pixels)
3. Low Noise and High Intra-scene Dynamic Range
4. Sub-electron Noise

Low Noise CMOS Image Sensors

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Dark Noise in CMOS Image Sensors

1. Temporal Random Noise

- Dark Current (Shot Noise)
- Reset or kTC Noise
- Amplifier's noise (thermal and $1/f$ noise)
- Row (Horizontal) Noise

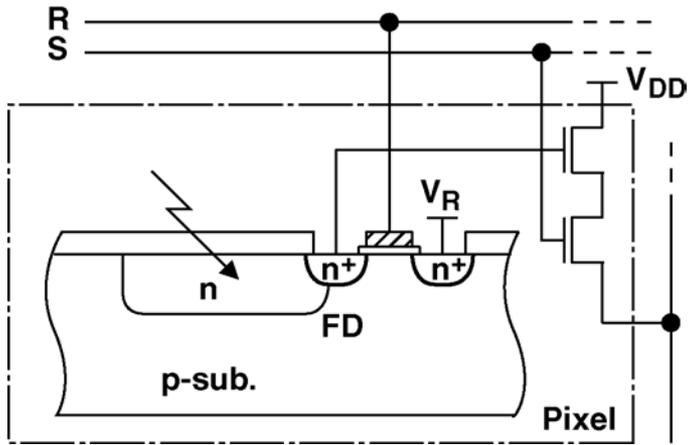
2. Fixed-Pattern Noise

- Pixel Source Follower's
- Column Readout Circuit's (Vertical FPN)
- Dark Current

Active Pixel Sensors

3Tr. APS

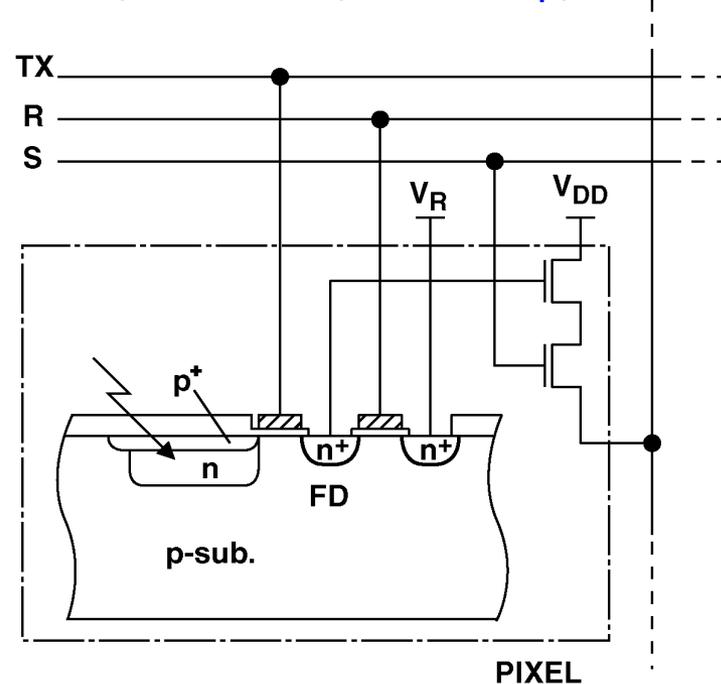
Chamberlain, IEEE-JSSC '69



- Used in end of 90's as a first cell-phone camera.
- kTC noise is NOT cancelled.
- Large dark current
- Conversion gain is determined by PD Cap.

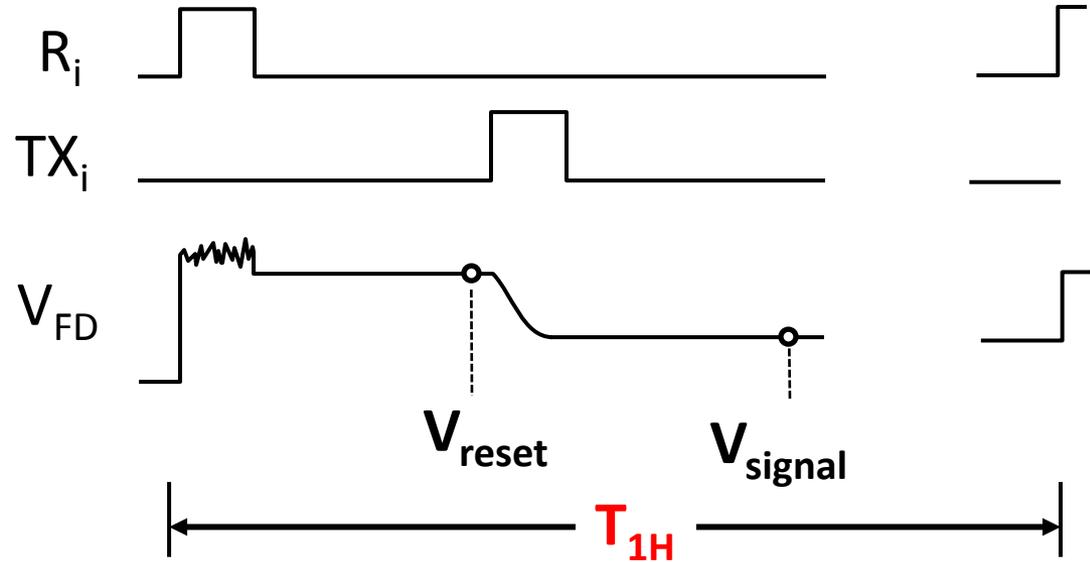
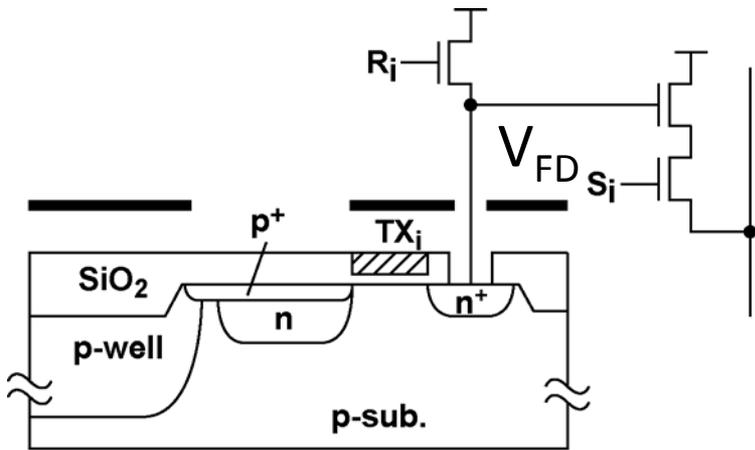
4Tr. APS (In-pixel charge transfer)

Lee et al., E. Fossum, Workshop, CCD & AIS, 1995.



- kTC noise is cancelled.
- Low dark current due to pinned photodiode
- High conversion gain due to small floating diffusion capacitance.

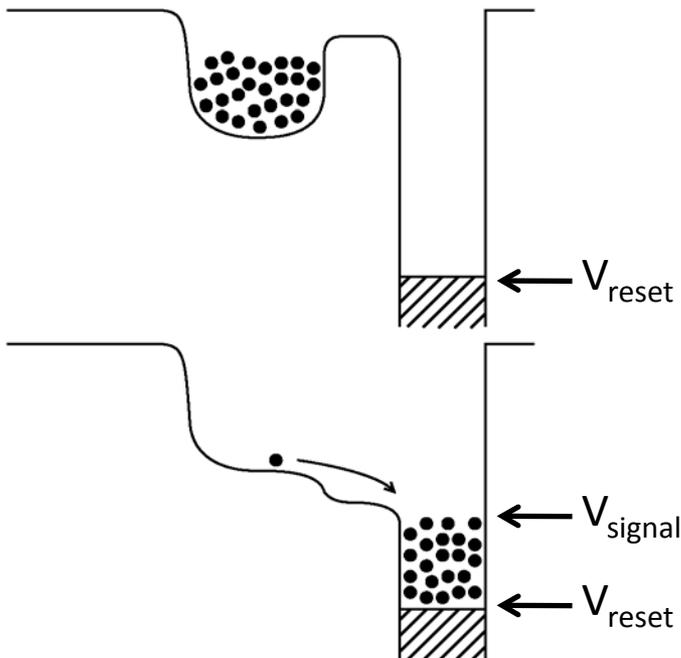
Readout Operation in CIS



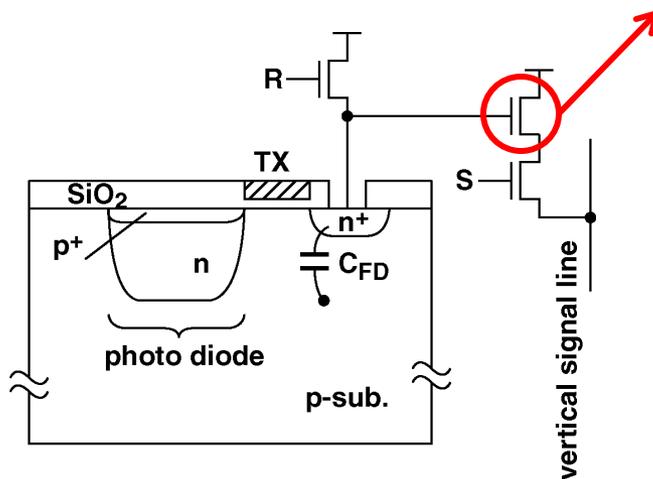
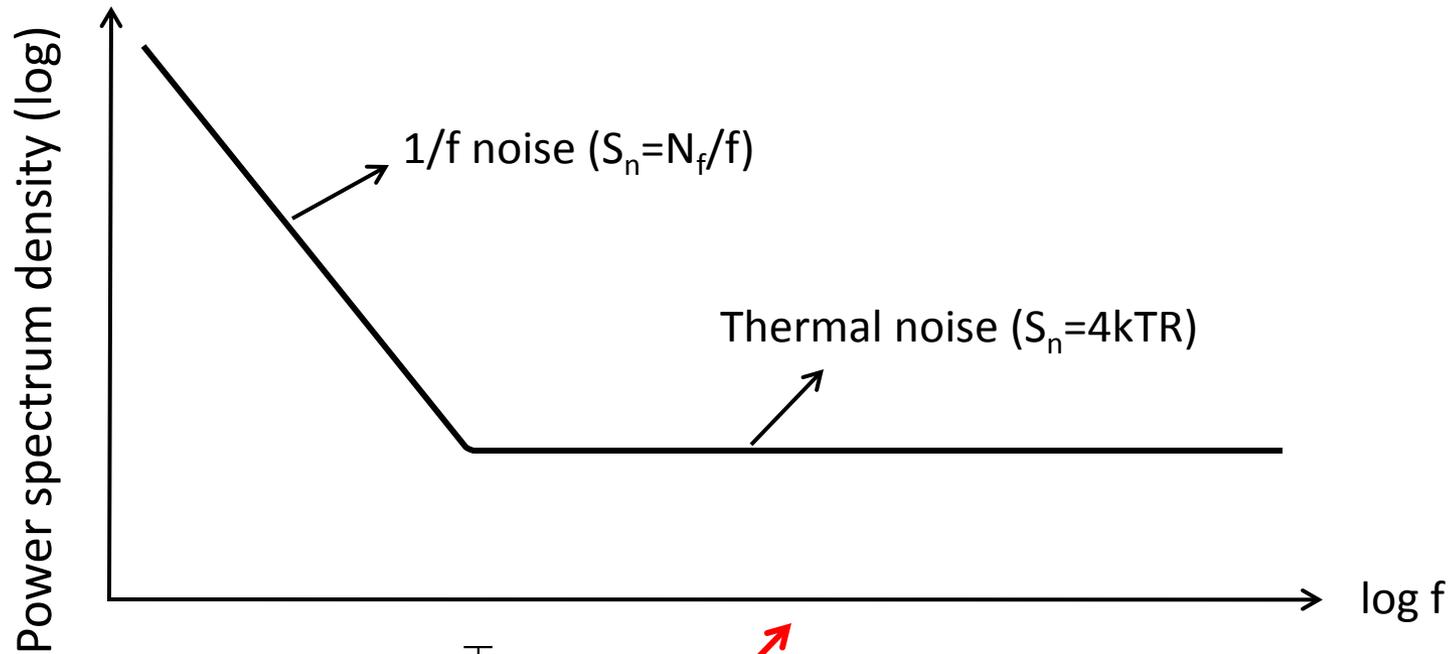
CDS (Correlated Double Sampling)

$$V_{out} = V_{signal} - V_{reset} \propto Q_s / C_{FD}$$

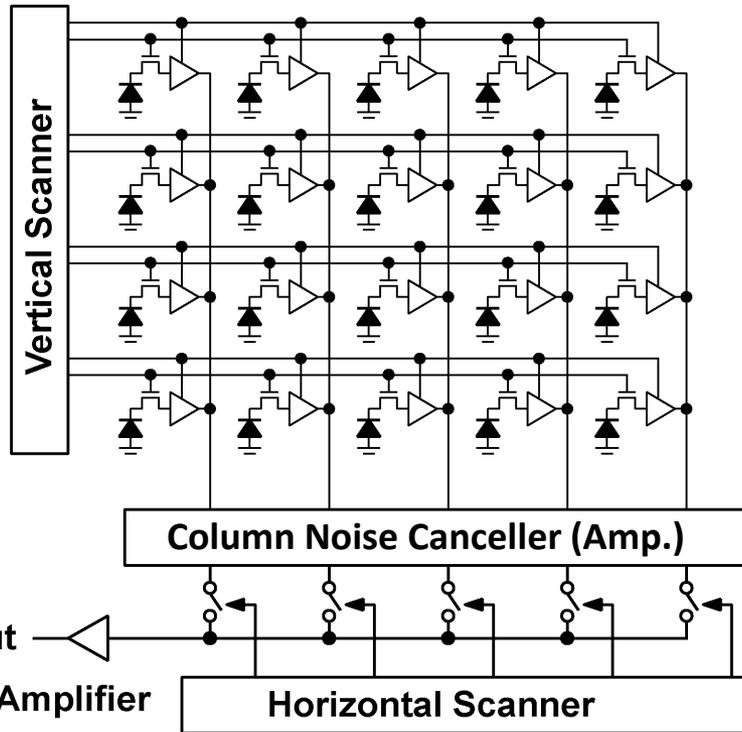
- Fixed Pattern Noise Cancelling
- kTC(Reset) Noise Cancelling



Thermal noise and 1/f noise in CMOS image sensors



Circuits' Noise in CMOS Image Sensors



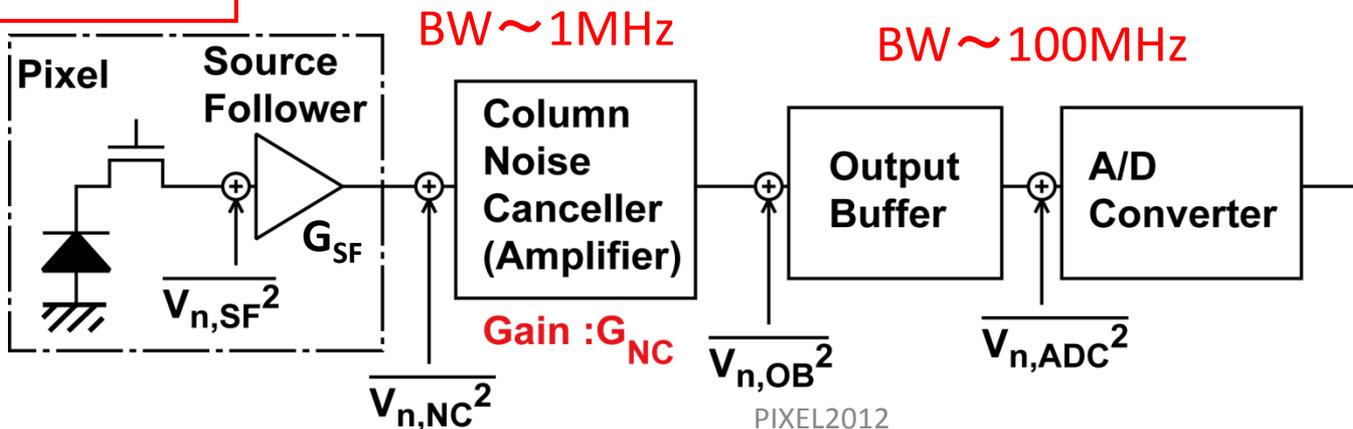
Input-Referred Noise (if $G_{SF}=1$)

$$\overline{V_{n,in}^2} = \overline{V_{n,SF}^2} + \overline{V_{n,NC}^2} + \frac{1}{G_{NC}^2} (\overline{V_{n,OB}^2} + \overline{V_{n,ADC}^2})$$

$$\cong \overline{V_{n,SF}^2} + \overline{V_{n,NC}^2} \quad (G_{NC} \gg 1)$$

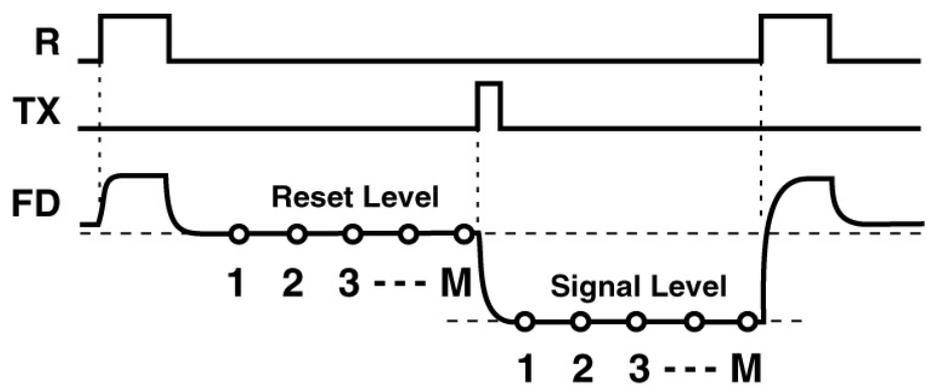
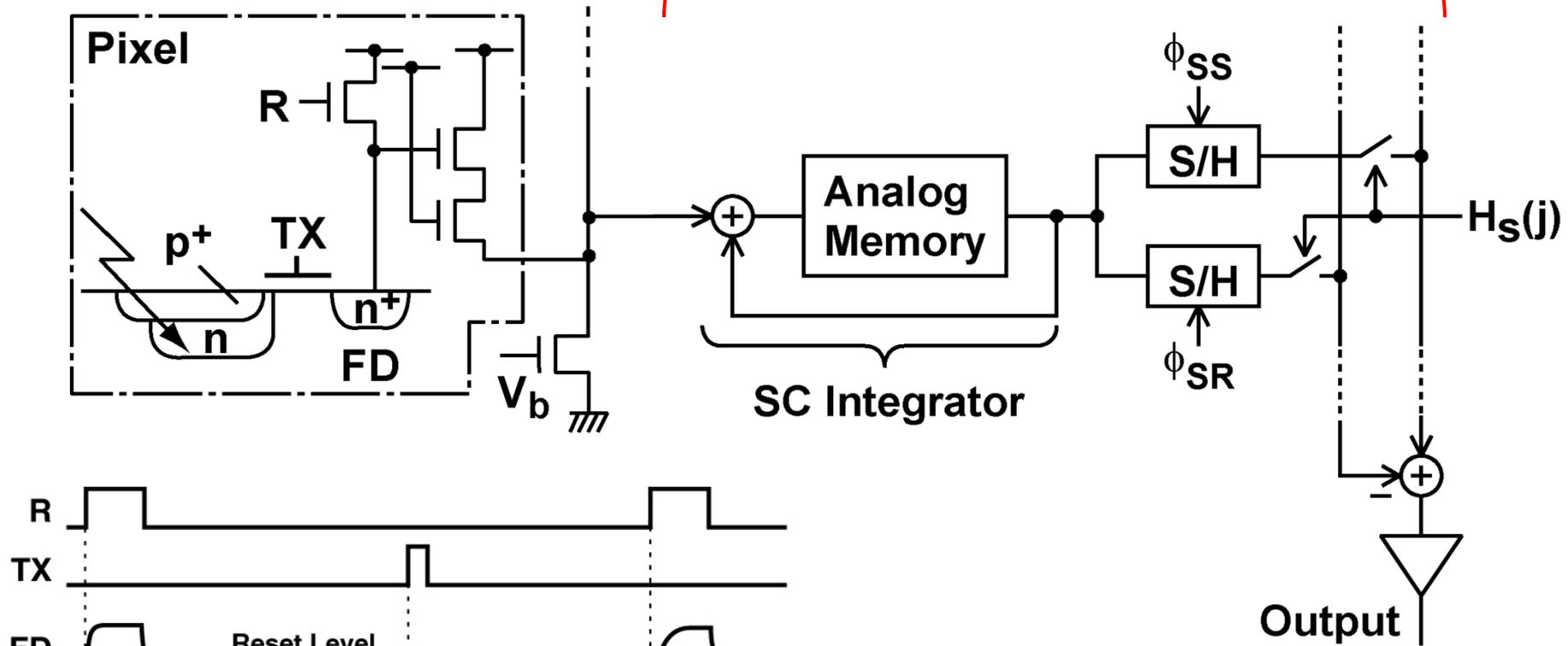
→ Gain of column amplifier greatly reduces wideband circuit noise.

Signal Chain



Column-Parallel Correlated Multiple Sampling

Column



$$V_{OUT} = \sum_{i=1}^M (V_R(i) - V_S(i))$$

M-time Sampling has a gain of $M \rightarrow$ Noise Reduction

Noise Reduction Effect of Correlated Multiple Sampling

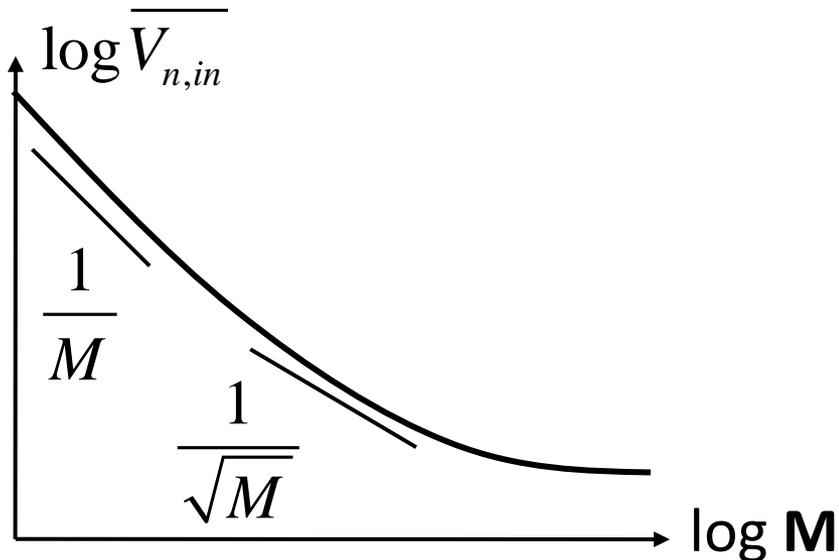
Input Referred Noise

$$\overline{V_{n,in}} \cong \sqrt{\overline{V_{n,1/f}}^2 + \frac{\overline{V_{n,th}}^2}{M} + \frac{\overline{V_{n,OB}}^2}{M^2}}$$

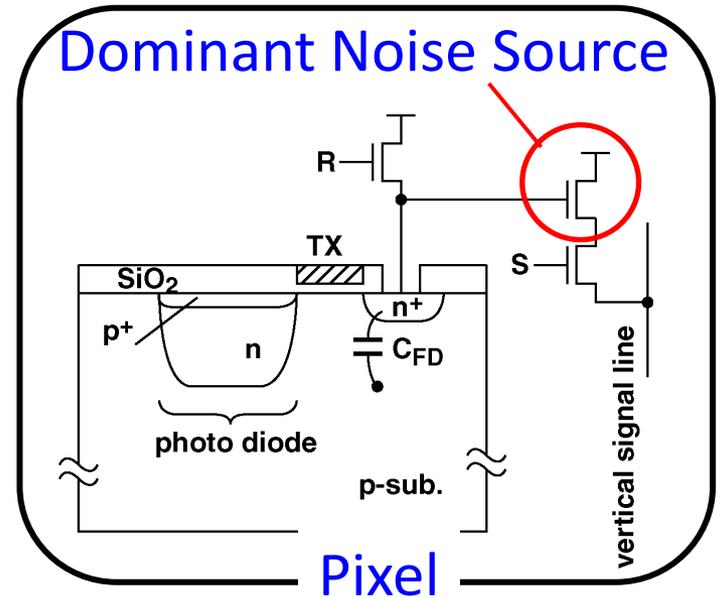
$\overline{V_{n,1/f}}^2$: 1/f Noise of S.F. for M=1.

$\overline{V_{n,th}}^2$: Thermal Noise of S.F. for M=1.

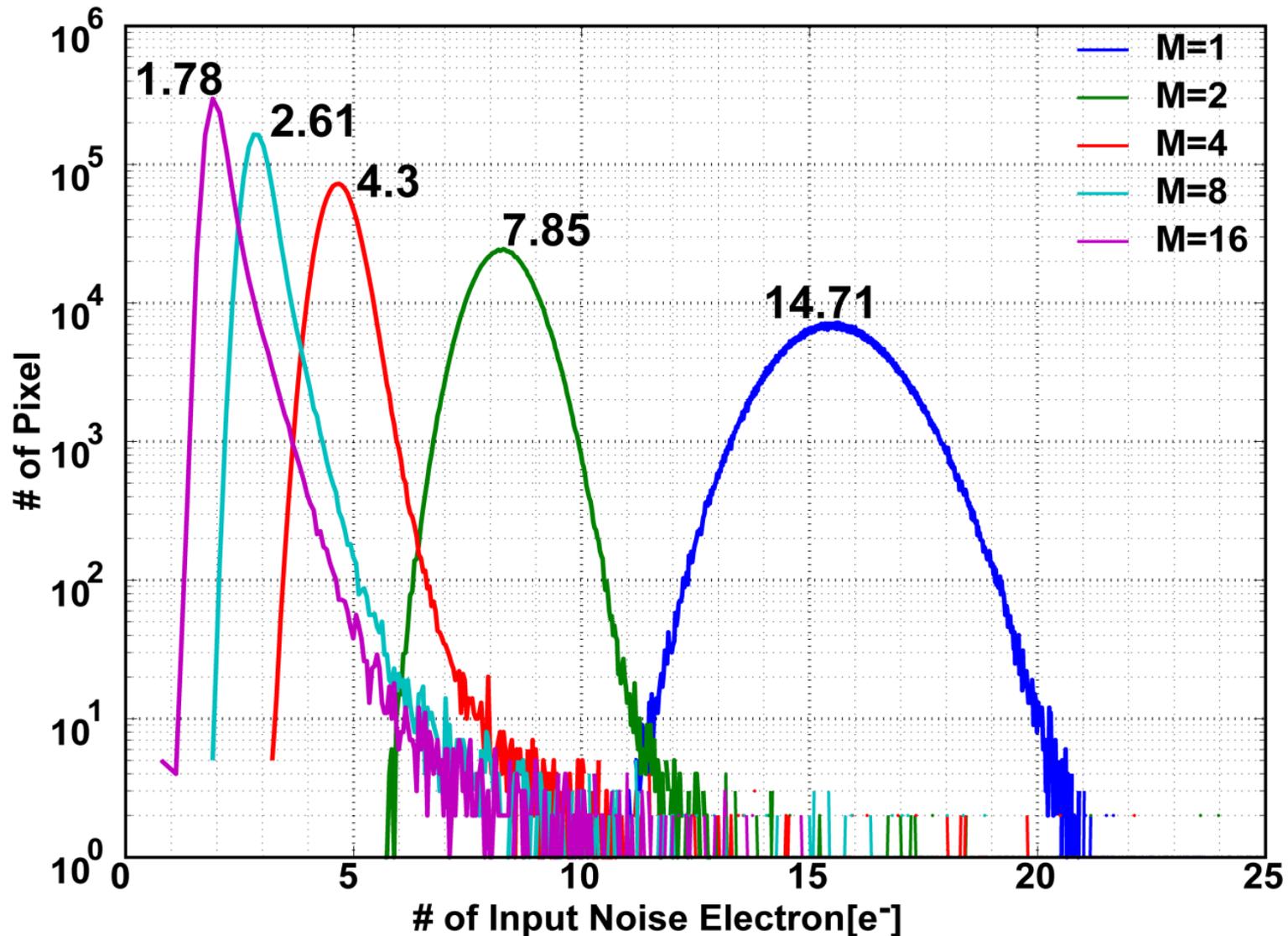
$\overline{V_{n,OB}}^2$: Noise of wideband output buffer



Dominant Noise Source



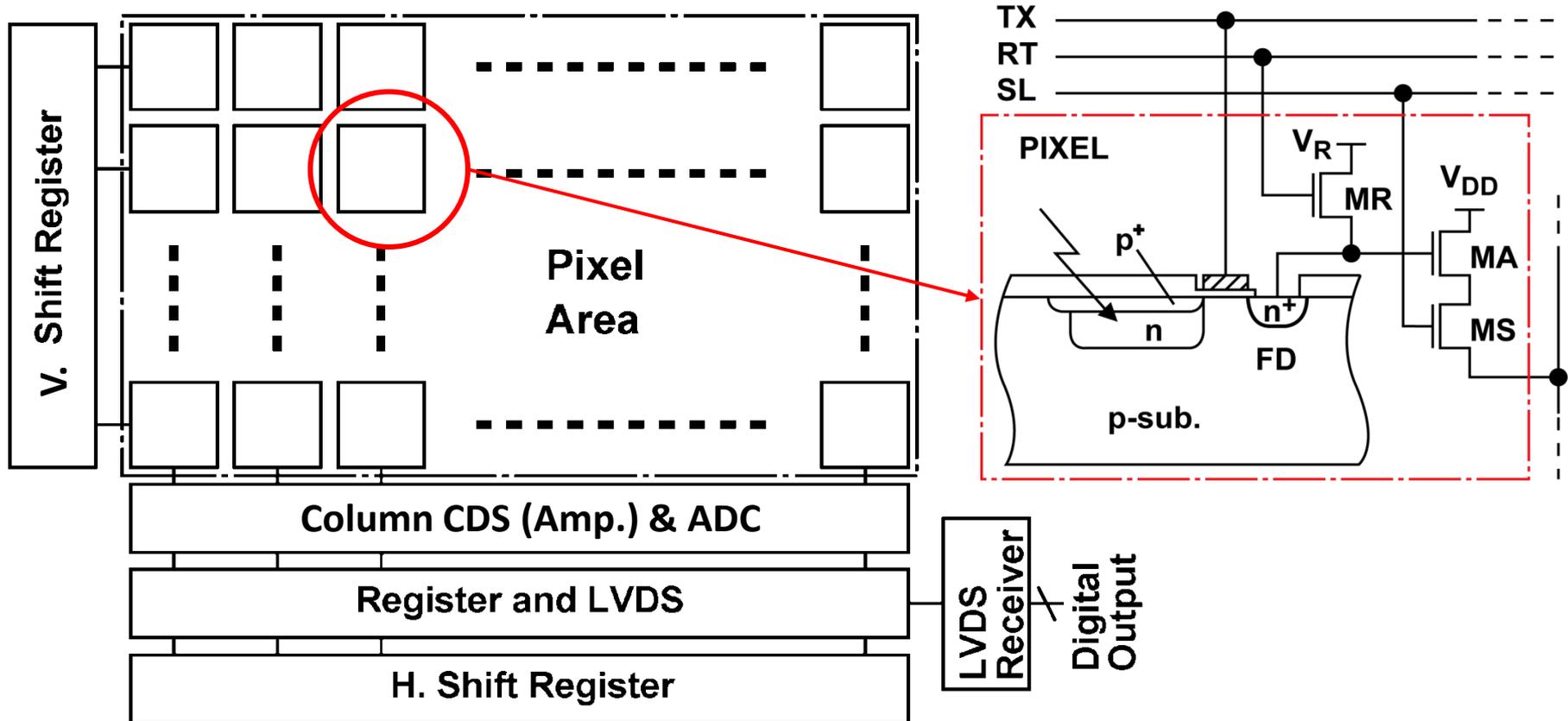
Noise Histogram of 1Mpixel CMOS Imager



Low Noise CMOS Image Sensors

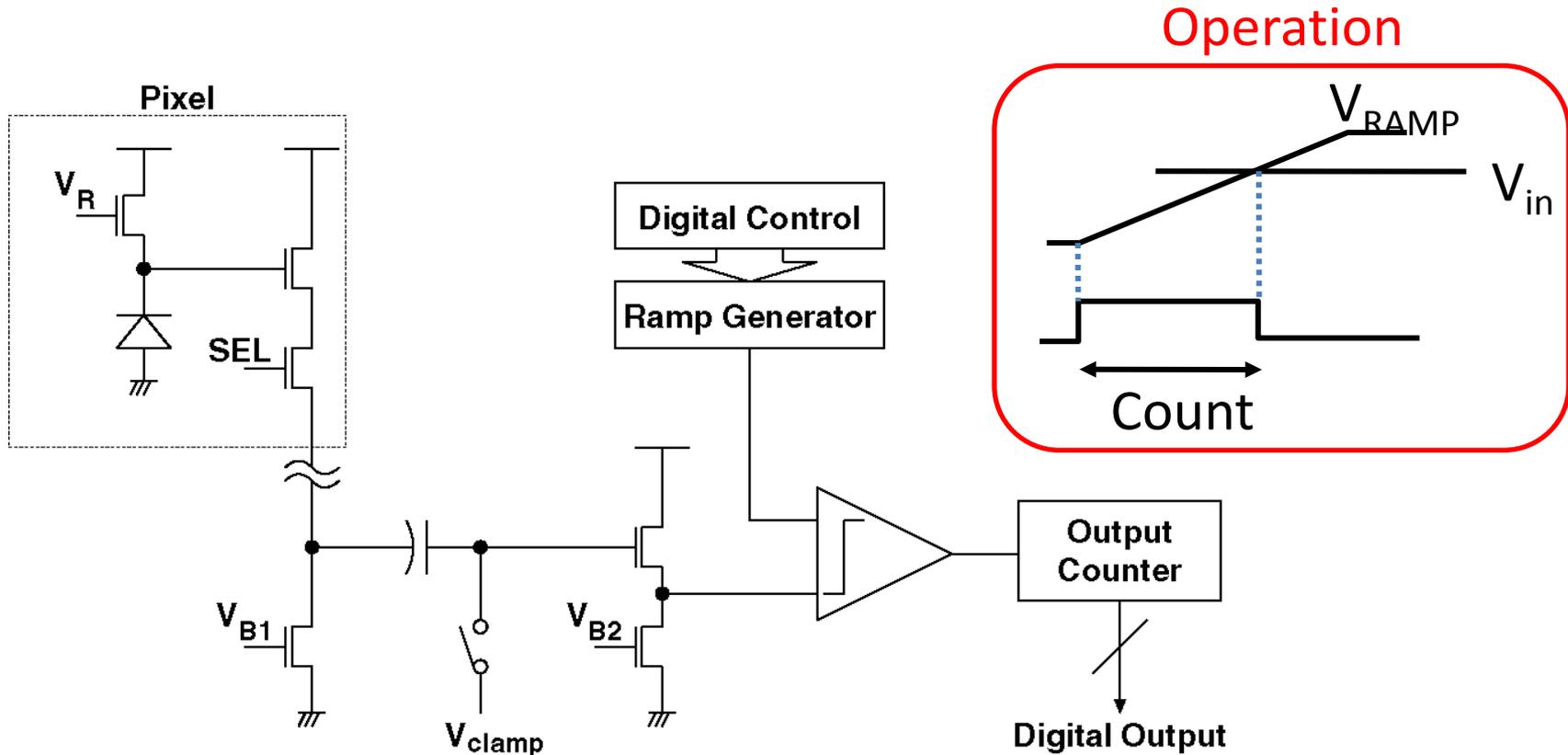
1. Low Noise ($<2e^-$)
2. Low Noise at High Pixel Rate (= frame rate x # of pixels)
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CIS Using Column ADC



- High-speed A/D conversion Using 1-D Parallel Processing
- High-speed low-noise digital signaling like LVDS (low-voltage differential signaling) is used.
- Digital H. Read is 10times faster than Analog.
(Analog : several 10MHz, Digital: several 100MHz)

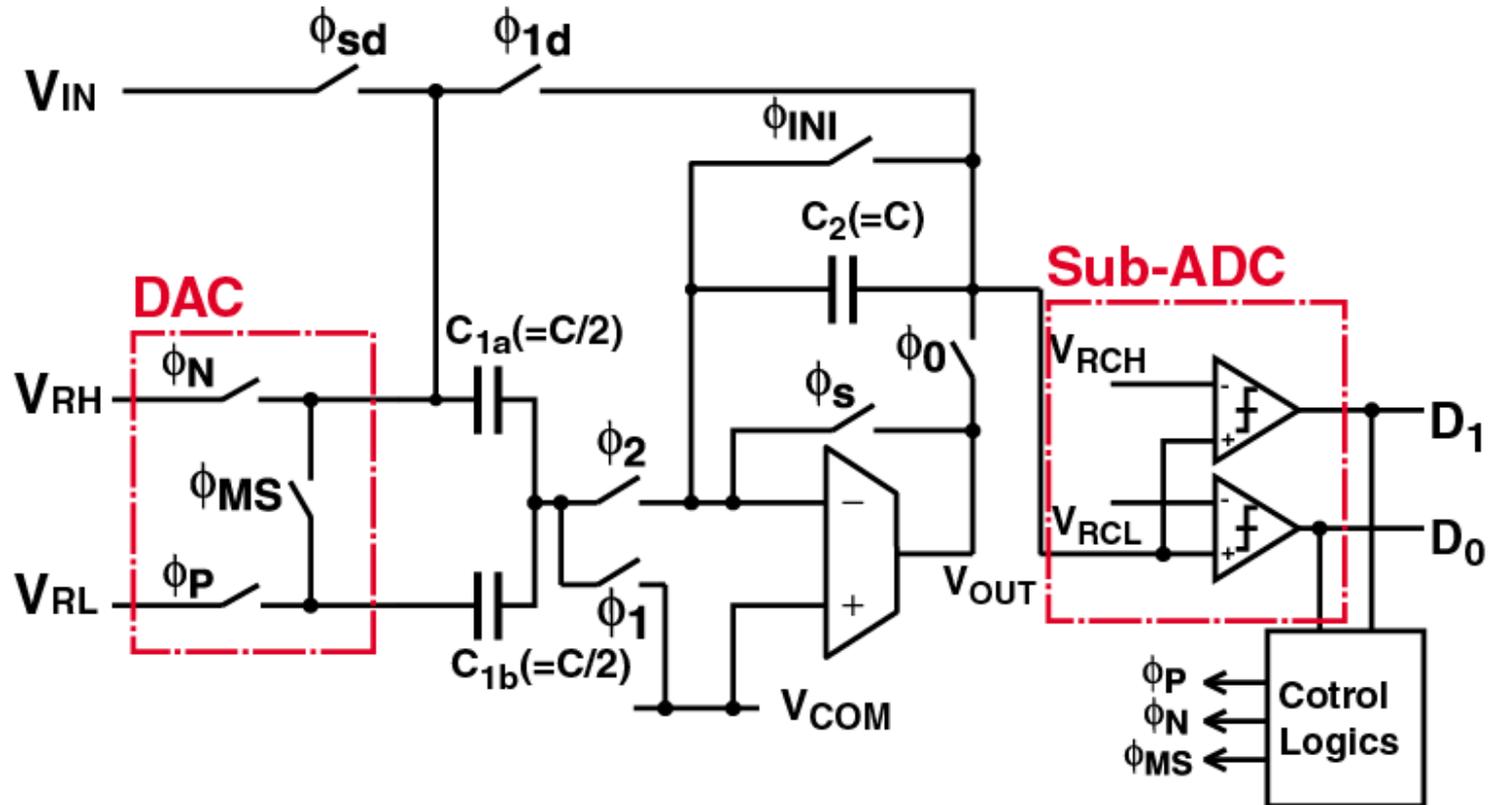
Single-Slope ADC



- Measure the time when V_{RAMP} equals to V_{in} using a counter.
- Basic Elements: Comparator and counter (or register)
- N-bit conversion requires 2^N clocks.

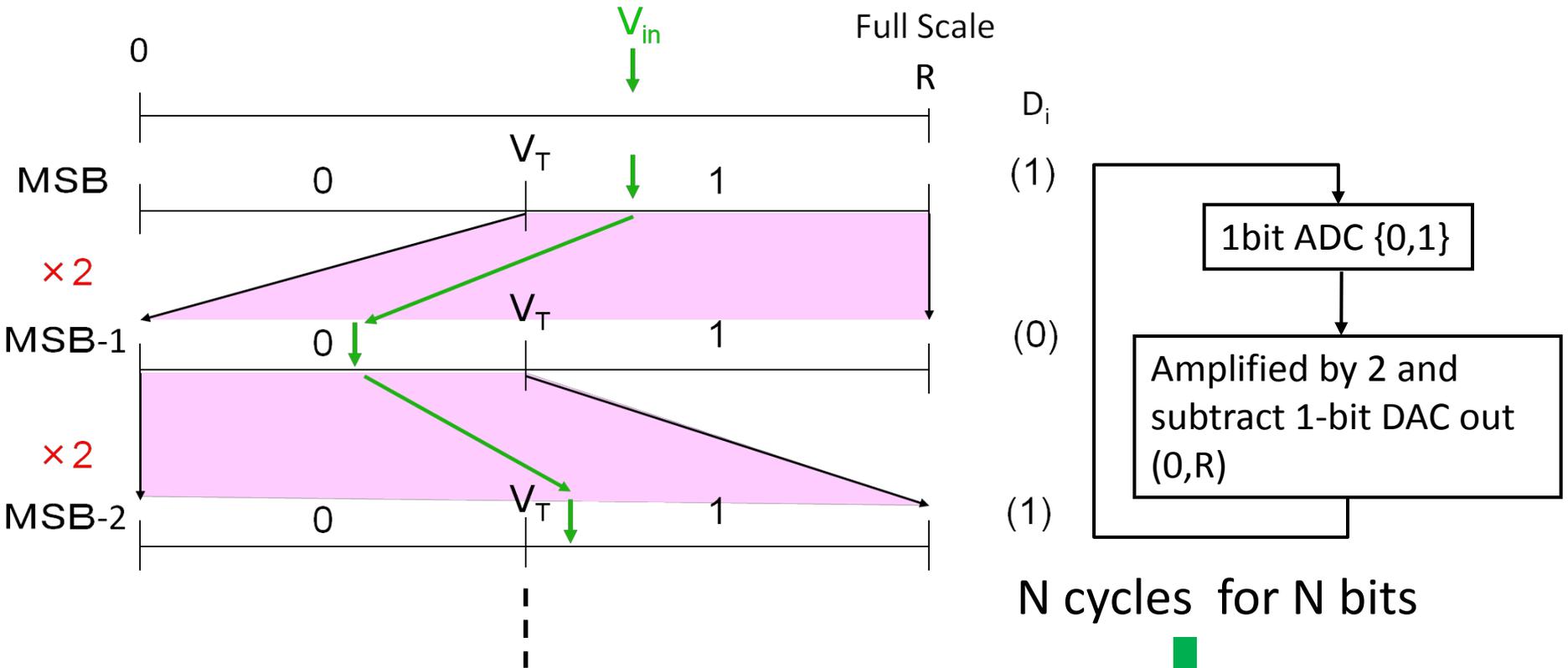
10b single-slope: Toshiba (ISSCC '00)

13b Column-Parallel Cyclic ADC



- Simplest Cyclic ADC (One Amp., Two Comparators, 3 Caps)
- **M-1 Cycles for M bits**
- Low Noise (4.9e-, gain=unity, 61uV/e-)

Operation of Cyclic ADC

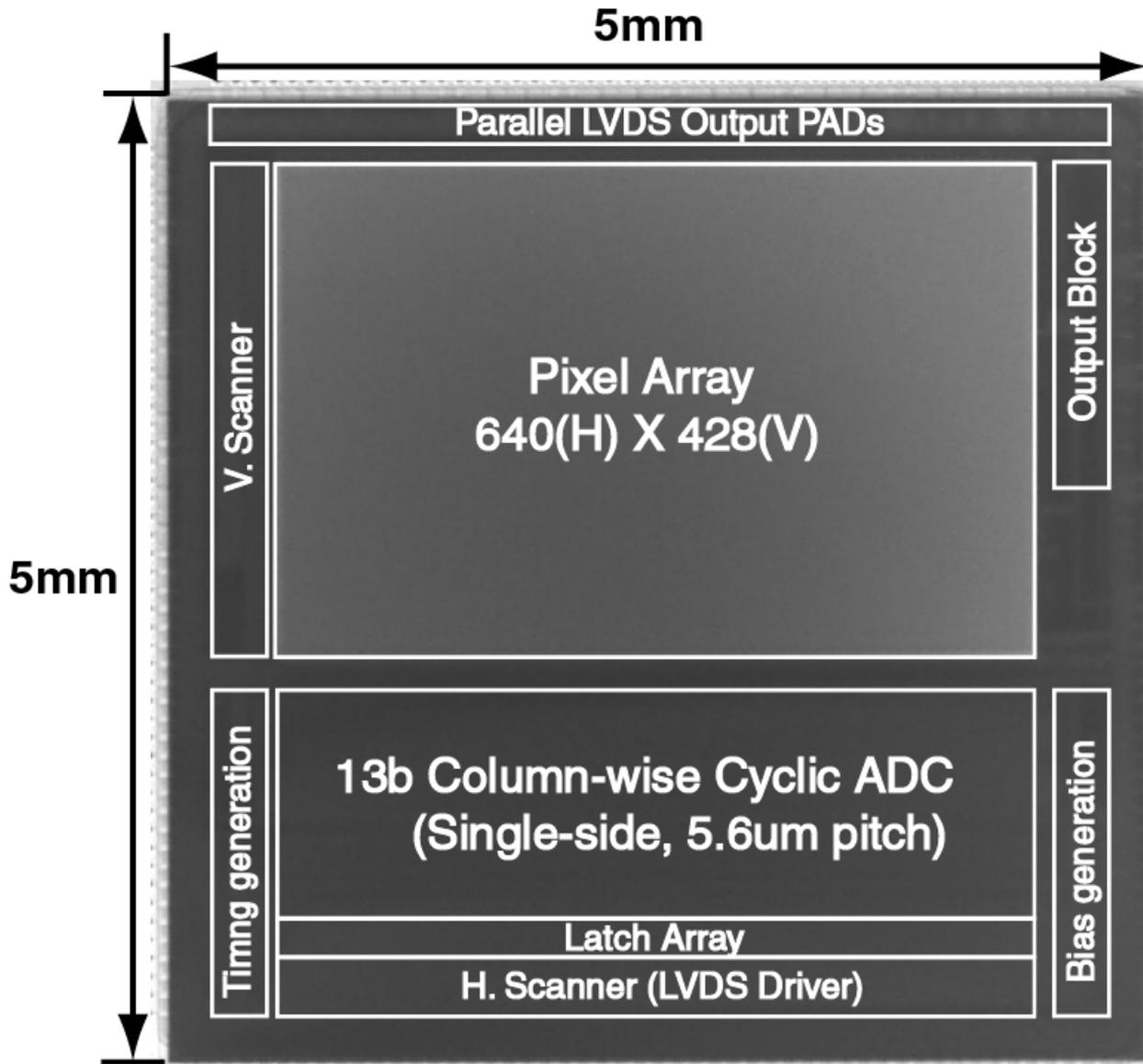


Basic Operation:

$$X_i = 2X_{i-1} - D_{i-1} \times R$$

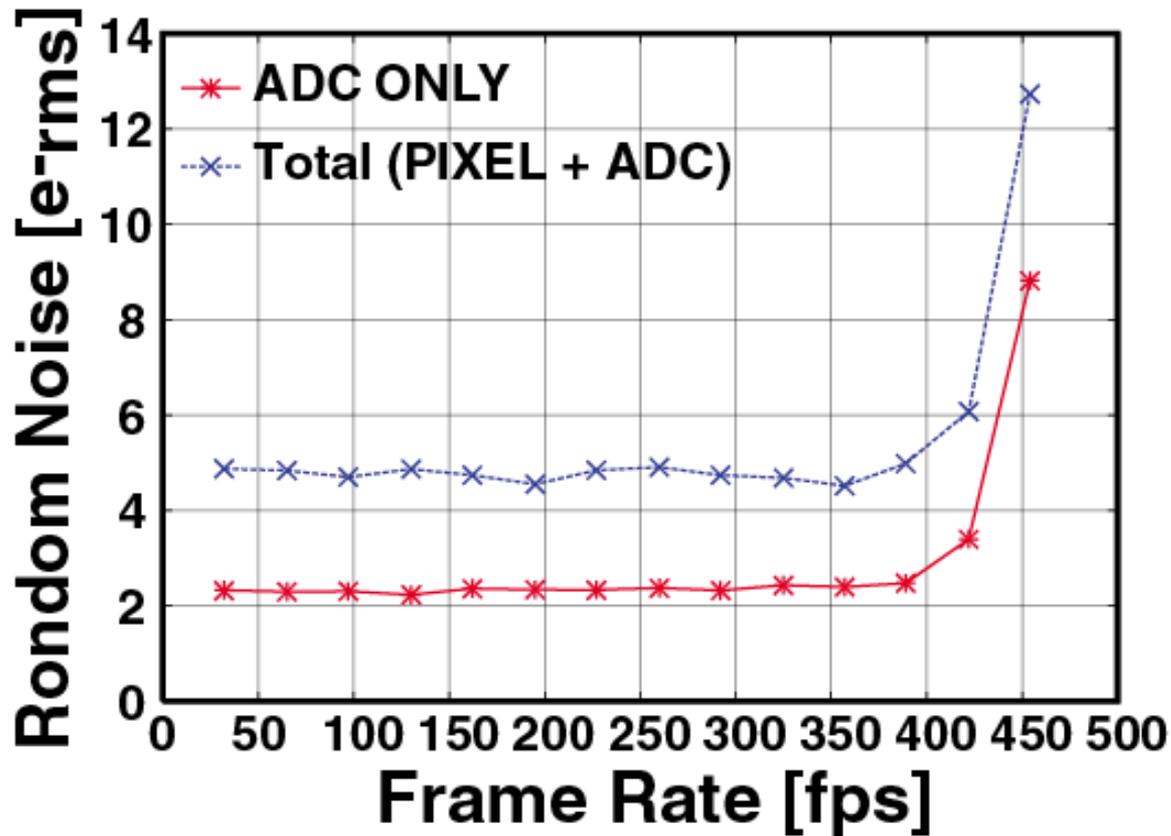
Actual Implementation: 3-state $\{-1,0,1\}$ sub-ADC is used for relaxing comparator precision (N-1 cycles for N bits)

Implemented CMOS Imager



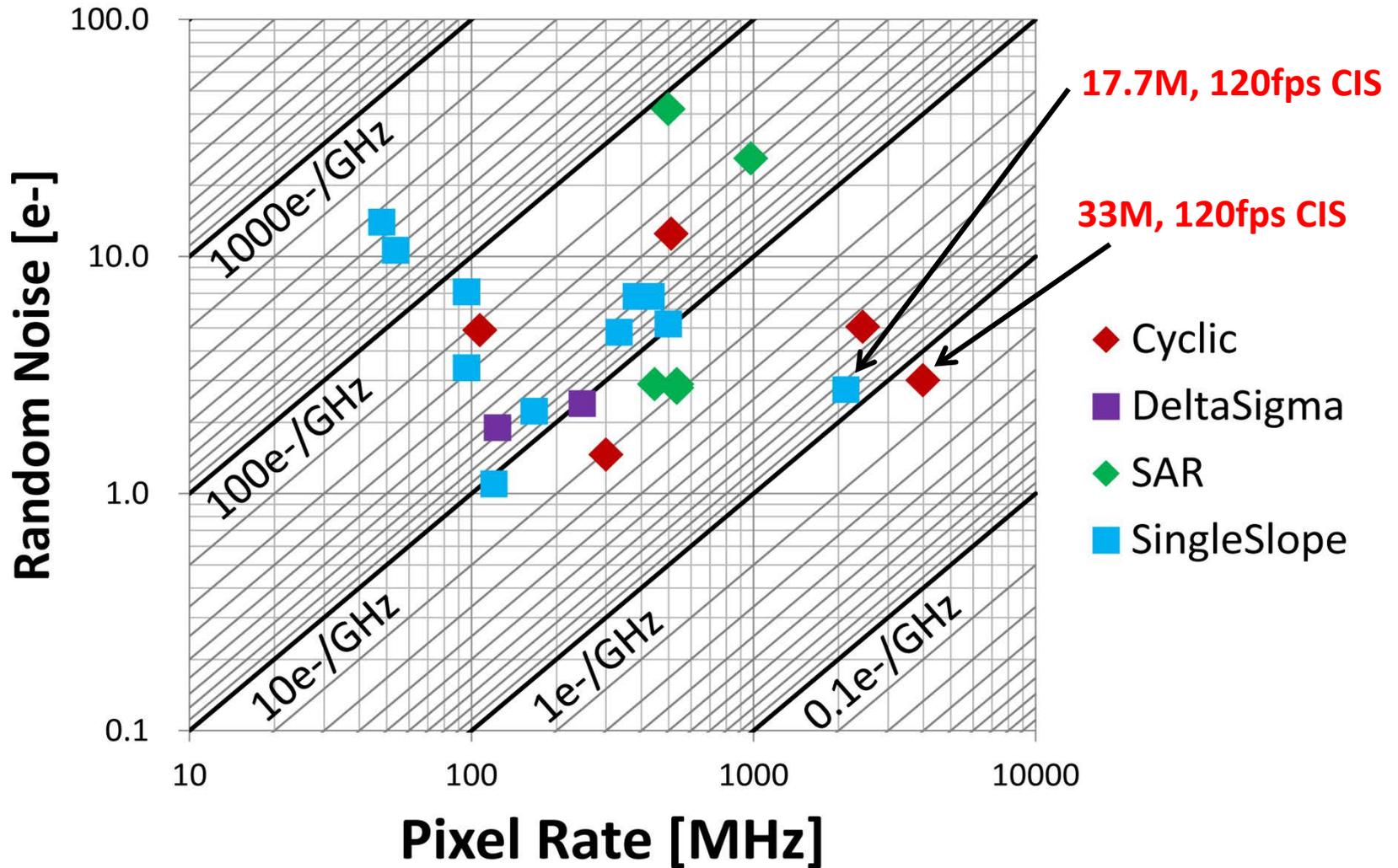
- ◆ 0.18 μ m CIS Process
- ◆ 4-Tr. Pinned photodiode
- ◆ Pixel Size : 5.6 μ m X 5.6 μ m
- ◆ ADC Resolution : 13b
- ◆ Frame rate : 340 fps

Noise Versus Frame Rate



- Low ADC Noise (2.5e⁻): Constant up to 390fps
- Low total noise without gaing (4.9e⁻_{rms})

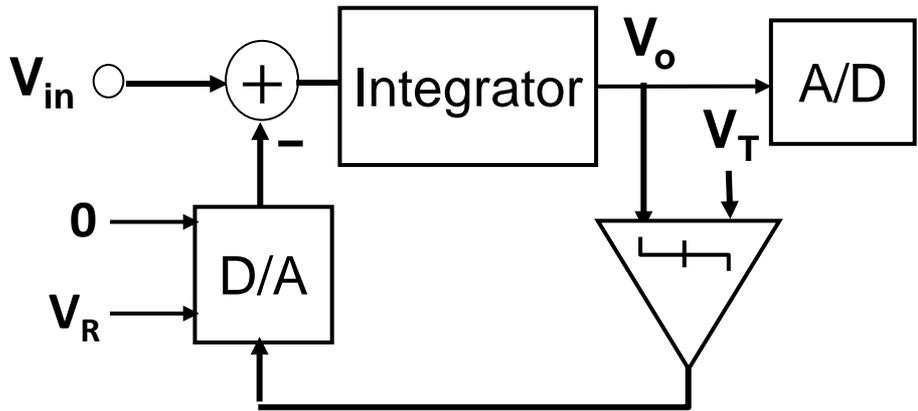
Noise – Pixel Rate of Digital CISs



Low Noise CMOS Image Sensors

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- 3. Low Noise and High Intrascene Dynamic Range**
4. Sub-electron Noise

Folding Integration Algorithm (Extended Counting)



$$D_i = \begin{cases} 1 & (\text{if } V_i \geq V_T) \\ 0 & (\text{if } V_i < V_T) \end{cases}$$

$$V_o(i) = V_o(i-1)$$

$$+ V_{in}(i) - \begin{cases} V_R & (\text{if } D_{i-1} = 1) \\ 0 & (\text{if } D_{i-1} = 0) \end{cases}$$

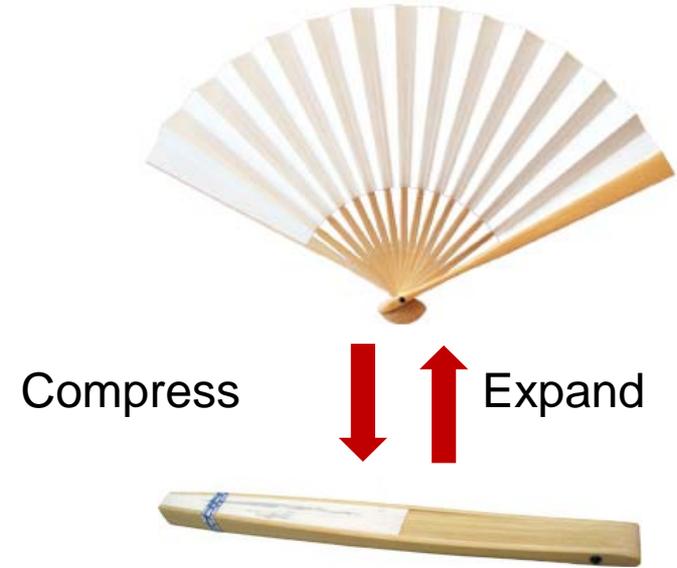
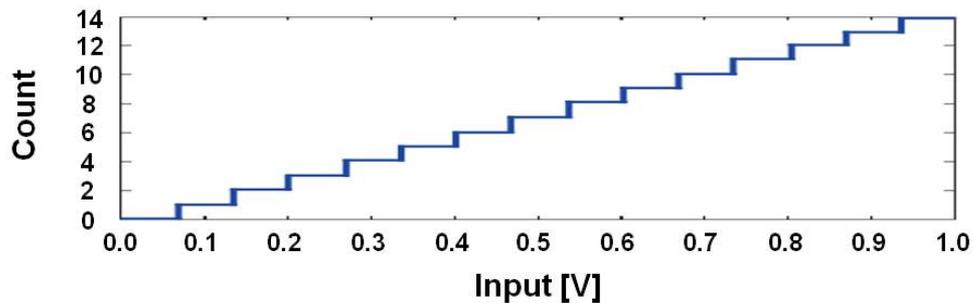
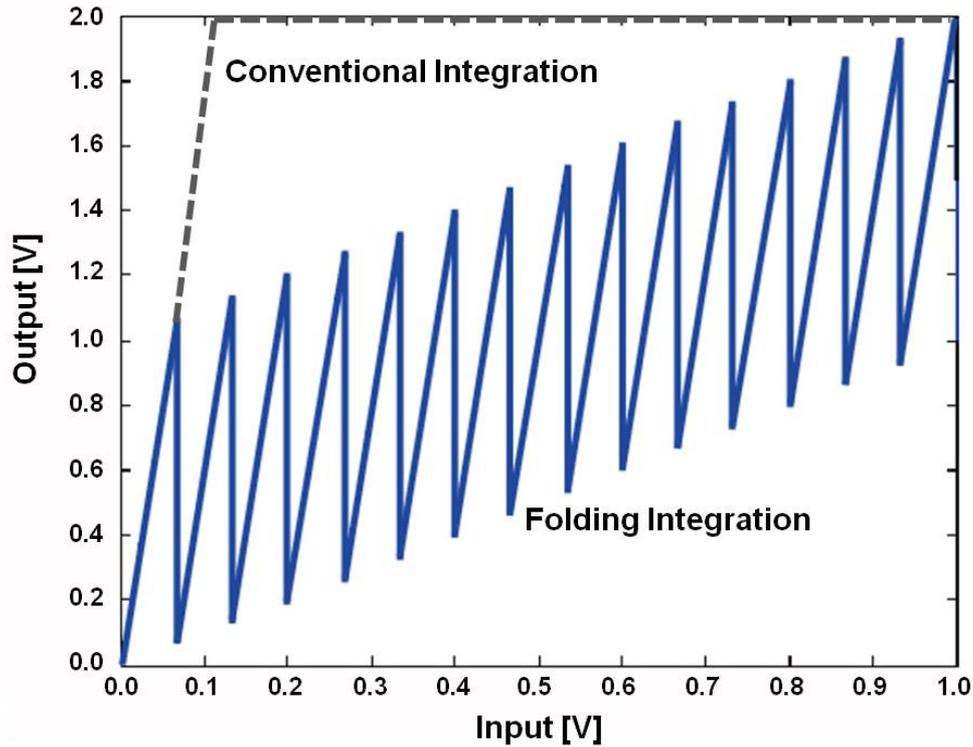
M-time Sampling : Gain of M

$$V_o(M) = M \times \overline{V_{in}} - N \times V_R$$

N : Number of 1's

~ Amplified by a gain of M, while compressing V_o in the same range of V_{in} (or $2 \times V_{in}$).

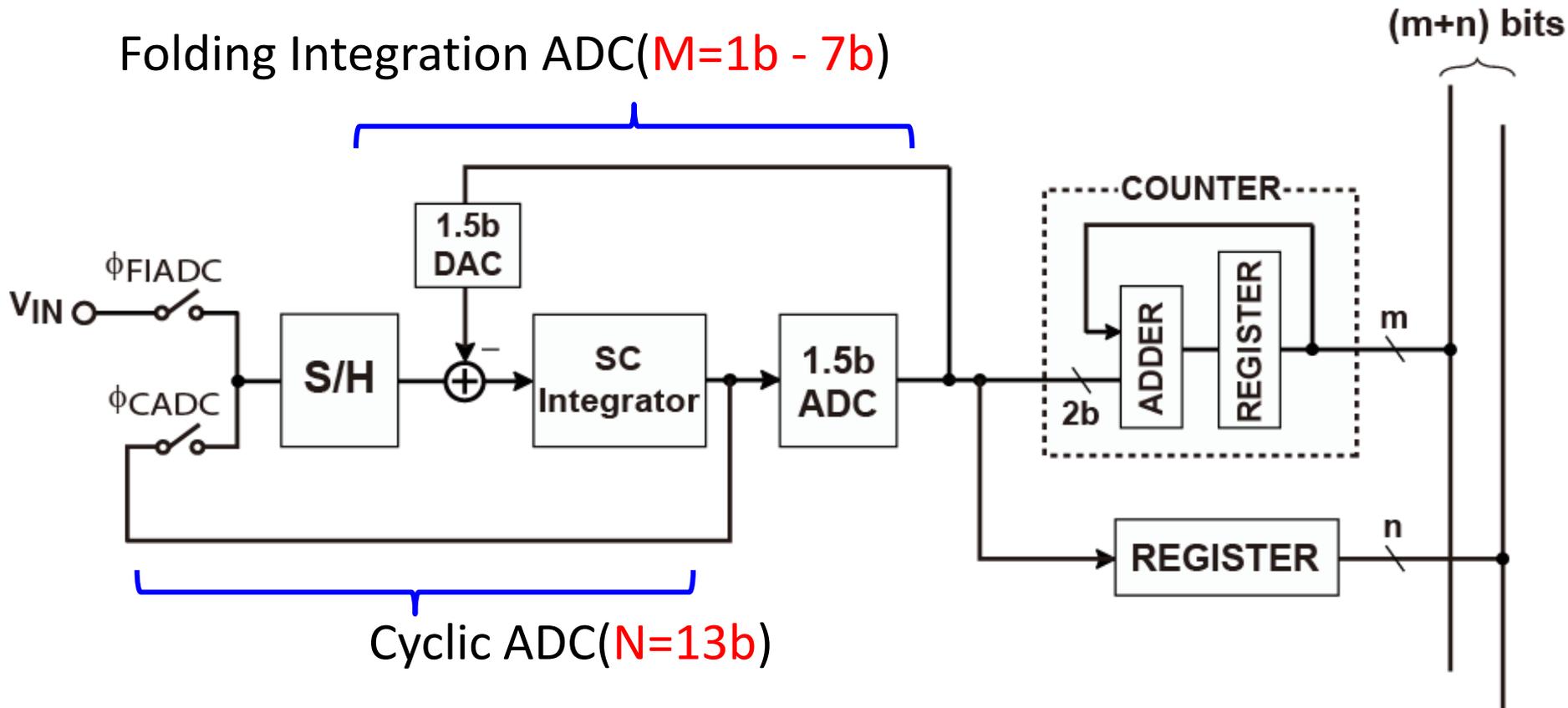
Transfer Curve of the Folding-Integration ADC (M=16)



- Output signal is compressed into 1 to 2V by folding operation.
- # of counts is used for coarse ADC. Cyclic ADC is used for the analog output.
- Folding integration is also known as extended counting*.

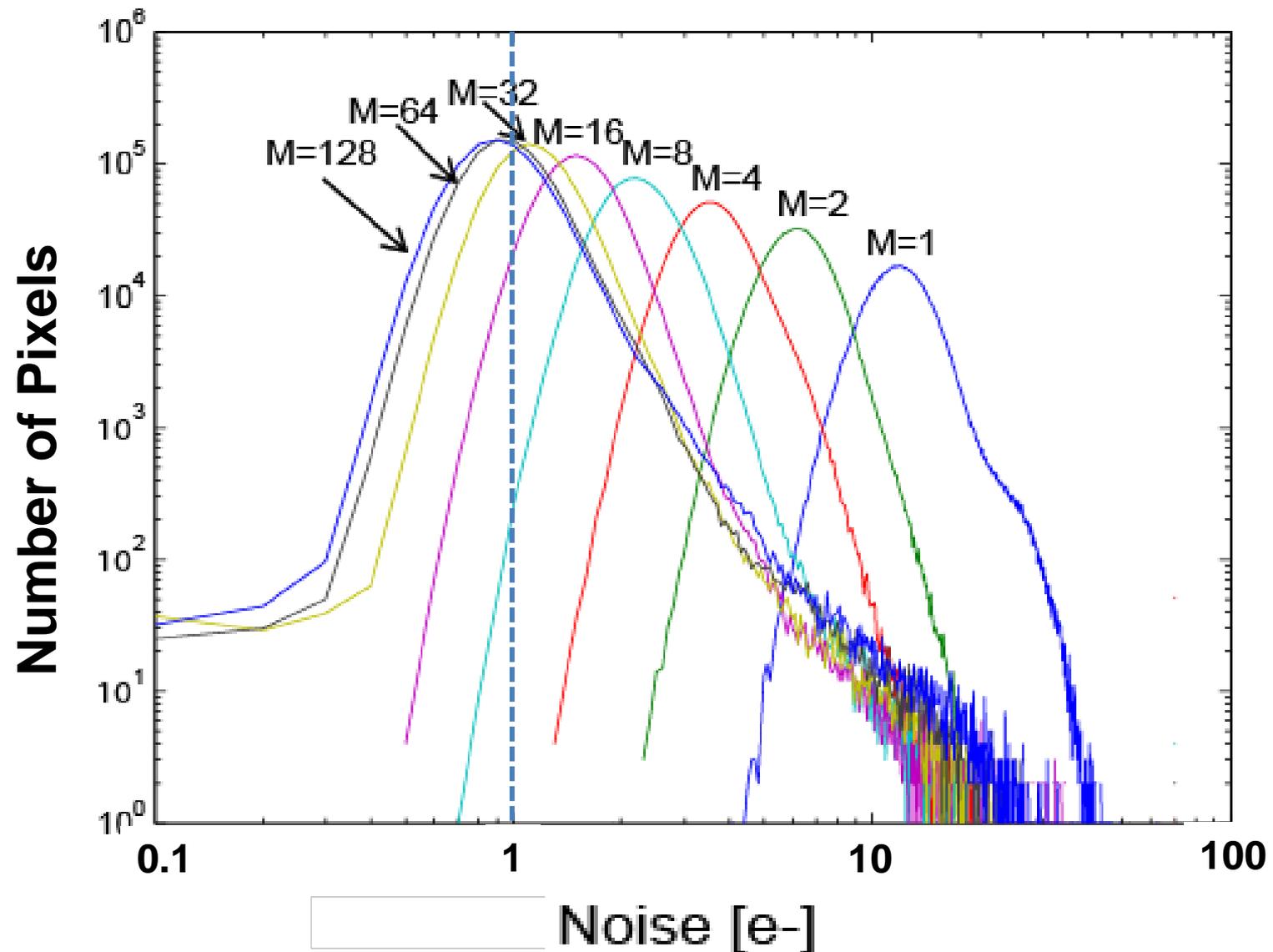
[*Jansson, IEEE Transactions on circuits and systems, 1995]

Block Diagram of the Folding Integration/Cyclic ADC

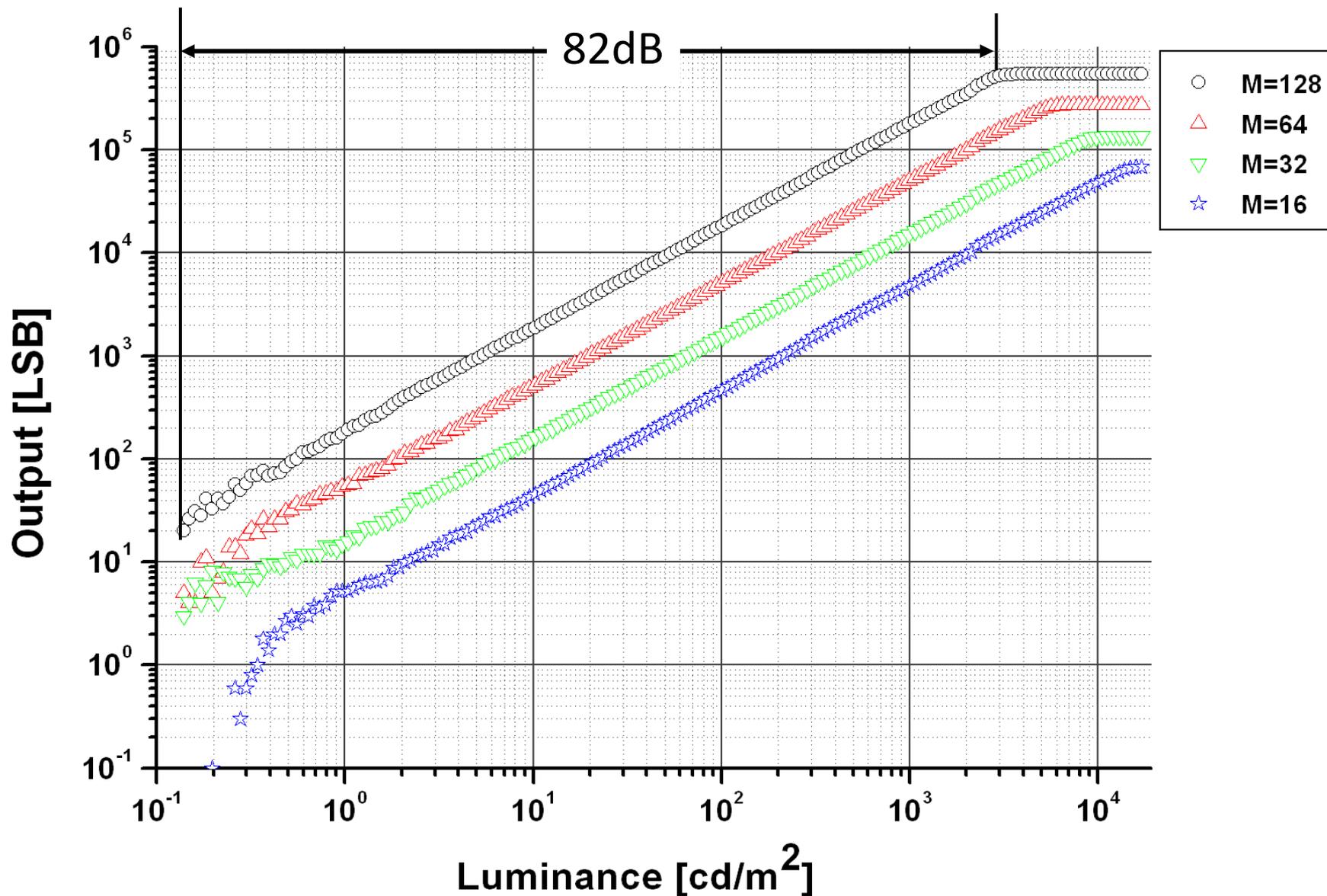


- The total resolution is $M+N-1$ [bits], very high gray-scale resolution (18b).
- The analog core is used for both the folding-integration and cyclic ADCs. (No additional analog circuits than that for cyclic ADC)

Noise Histogram of 1Mpixel CIS

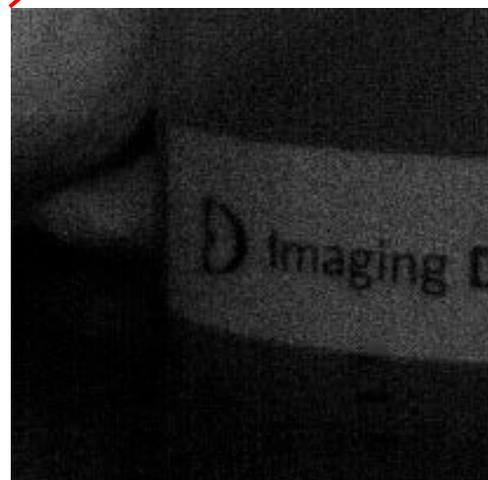


Linearity of Photo Response



EM-CCD (Gain : x800, Cooling: -10°C, 4fps)

HS-CMOS (Gain : x768, Cooling: 10°C, 4fps)

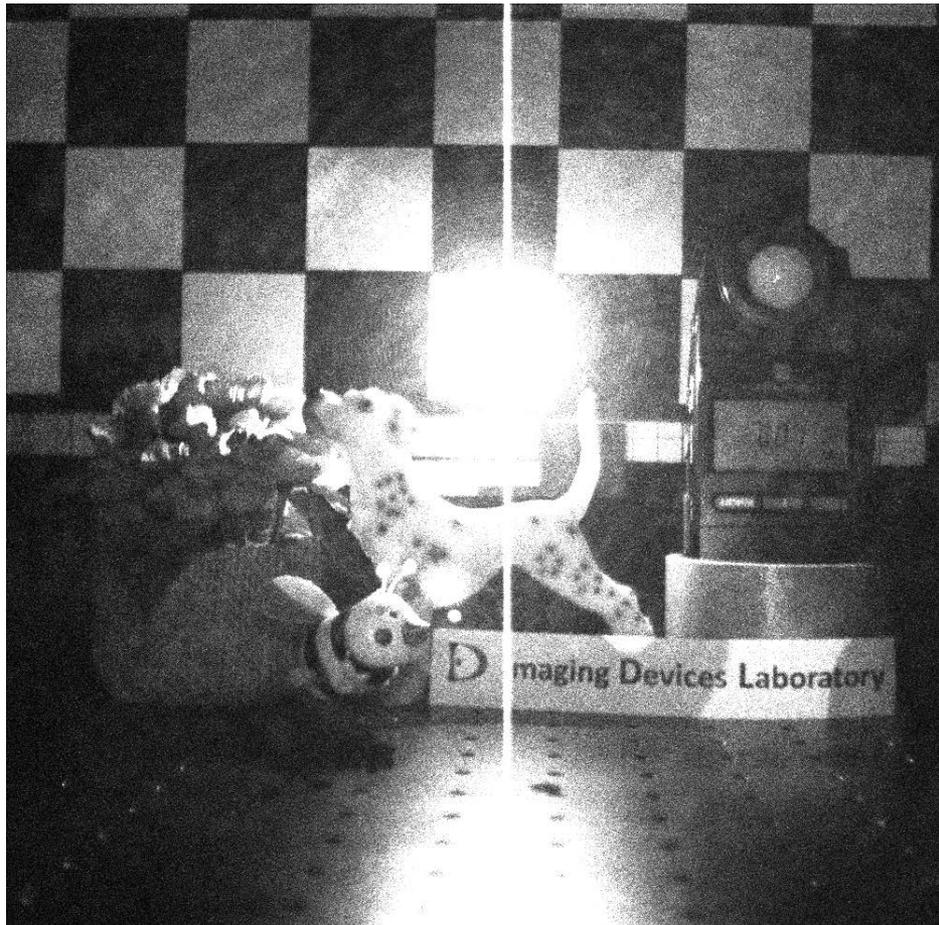


Illumination
: 0.005lx

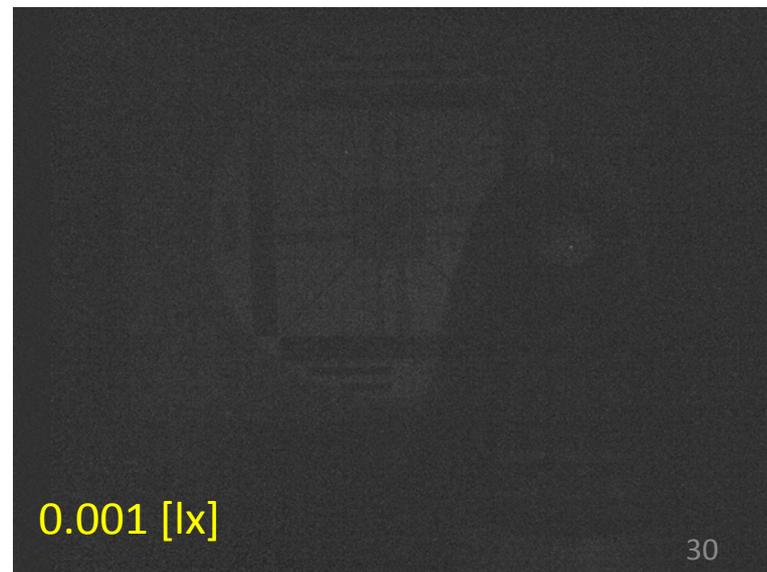
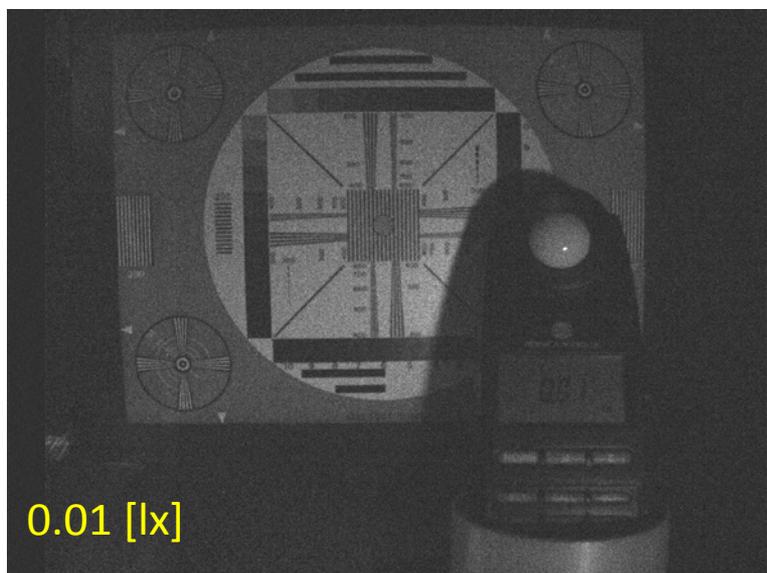
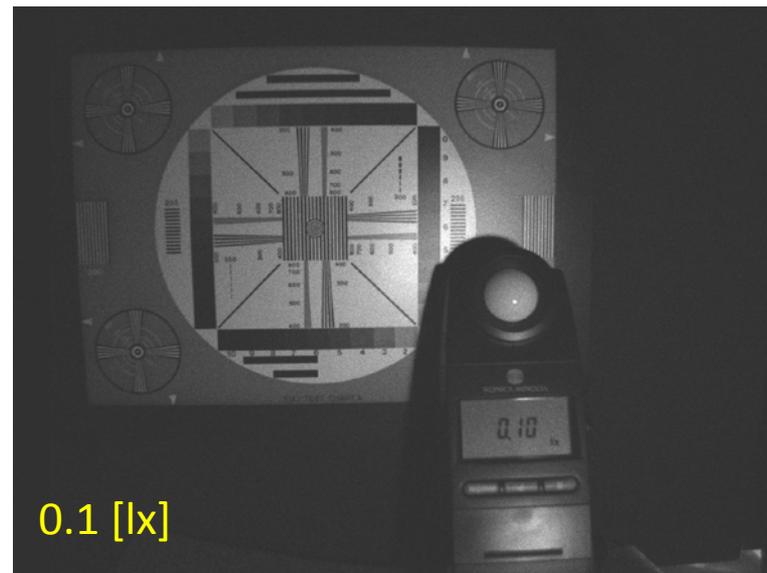
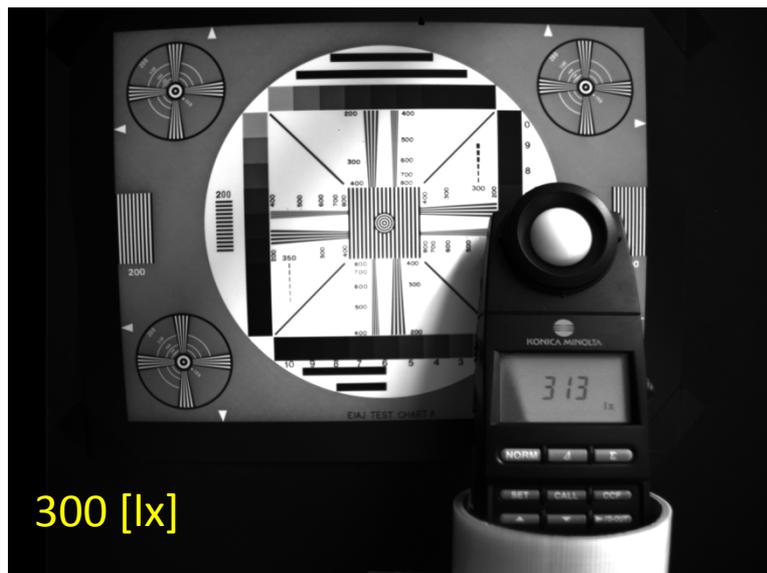
Dynamic Range Comparison

(EM-CCD)

(HS-CMOS, $\gamma=1.65$, DR=82dB)



Low Light Level Image (1.3M, 7.1um, @30fps, 1.2e-)



Low Noise CMOS Image Sensors

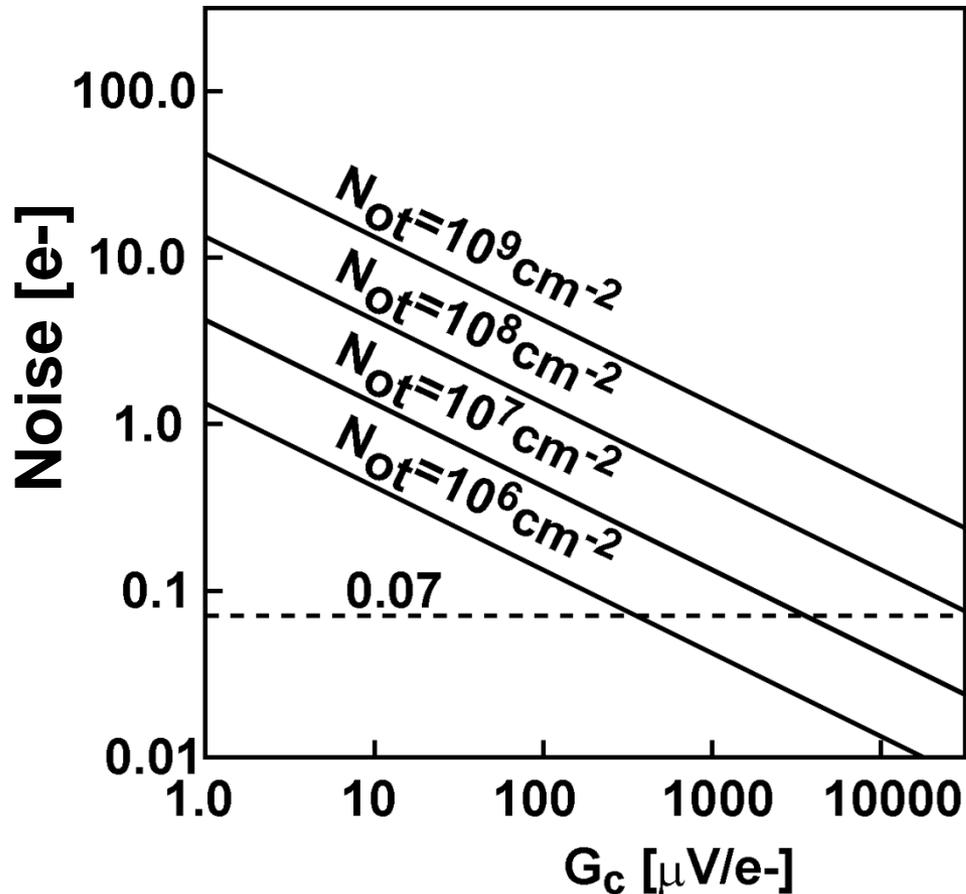
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Reports on Low-Noise CISs (<1.1e-)

Technique Used	Noise		Conversion Gain [$\mu\text{V}/e^-$]	Reference
	[μV]	[e^-]		
Column Amplifier (G=32), Single-Slope ADC (SSADC)	n. a.	0.8	n.a. (2.1DN/ e^-)	IISW 2007
Multiple Sampling, Folding Integration/ Cyclic ADC	65 μV	0.95	67 $\mu\text{V}/e^-$	ISSCC 2011, JSSC (Jan.,2012)
Pseudo Multiple Sampling with SSADC	121 μV	1.1	110 $\mu\text{V}/e^-$	ISSCC 2010
PMOS Common-Source Pixel Amp.	260 μV	0.86	300 $\mu\text{V}/e^-$	ISSCC 2010
Buried Channel nMOS S. F. Multiple Sampling with SSADC	32 μV	0.7	45 $\mu\text{V}/e^-$	ISSCC 2012
nMOS S. F. with Switched Biasing	n. a.	0.5	n. a.	www.caeleste.com , 2011

Low 1/f Noise Pixel + Multiple Sampling Column ADC

How to realize 0.1e- Noise



1/f Noise Spectrum

$$S_{nf} = \frac{q^2 N_{ot}}{C_{ox}^2 A_G} \frac{1}{f} = \frac{N_f}{f}$$

N_{ot} : Effective Trap Density [cm^{-2}]
Presently, $10^7 \sim 10^8 \text{ cm}^{-2}$

$$G_c = G_{SF} \frac{q}{C_{FD}}$$

Highest Conversion gain
reported $\sim 300e^-$

- Low 1/f Noise Transistor : Small N_{ot}
- High Conversion Gain Charge Detector ($>1000 \mu\text{V}/e^-$)
(extremely small capacitance of $<0.1 \text{ fF}$)

Summary

- Pixel : Charge transfer active pixel with pinned photodiode (Low dark current, kTC noise canceling and high conversion gain)
- Low circuit noise : High gain column readout circuits (using multiple sampling and ADC)
- Low noise at high pixel rate : column ADC is the key
- Low noise and wide dynamic range : enabled by column readout circuits (Advantage of CMOS)
- Sub-electron noise imager: low $1/f$ noise pixel amplifier (further reduction: high conversion gain)